

# Semiconductor

## 1/3, 1/4, 1/5 Duty 80 Output LCD Driver

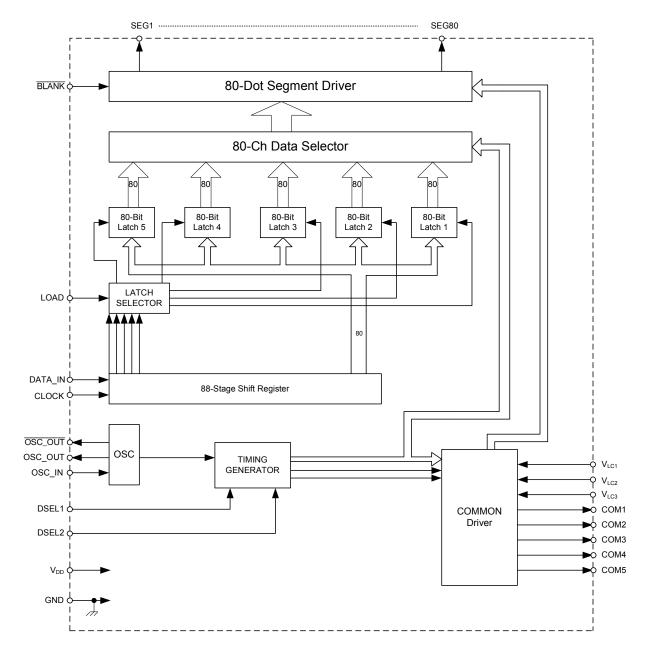
#### **GENERAL DESCRIPTION**

The ML9471 is a LCD driver for dynamic display providing 3-duty-switchable pins (1/3, 1/4, 1/5 duty). It can directly drive LCDs of up to 400, 320 and 240 segments when 1/5, 1/4 and 1/3 duty are selected respectively.

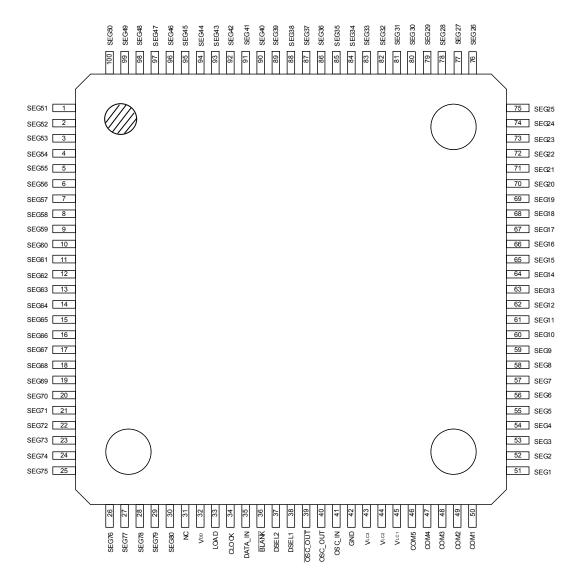
#### **FEATURES**

• Operatin g range					
Supply voltage	: 3.0 to 5.5 V				
Operating temperature range	$: -40 \text{ to} + 105^{\circ}\text{C}$				
Segment output	: 80 pins				
1/5 duty	: Up to 400 segments can be displayed.				
1/4 duty	: Up to 320 segments can be displayed.				
1/3 duty	: Up to 240 segments can be displayed.				
<ul> <li>Serial transfer clock frequency</li> </ul>	: 4 MHz				
<ul> <li>Serical interface with CPU</li> </ul>	:Through three input pins (DATA_IN, LOAD, and CLOCK)				
Built-in oscillator circuit for COMMC	ON signals				
One-to-one correspondence between i					
When input data is at "H" level	: Display goes on.				
When input data is at "L" level	: Display goes off.				
• The entire display can be turned off. (BLANK pin)					
• P ackage options					
100-pin plastic TQFP (TQFP100-P-14	414-0.50-K) (Product name: ML9471TB)				

#### **BLOCK DIAGRAM**



#### **PIN CONFIGURATION (TOP VIEW)**



**100-Pin Plastic TQFP** 

## **PIN DESCRIPTION**

Symbol T	уре		Description					
OSC_IN OSC_OUT OSC_OUT	 0 0	resistors and a capa the resistor connect	Pins for oscillation. The oscillator circuit is configured by externally connecting two resistors and a capacitor. Make the wiring length as short as possible, because the resistor connected to the OSC_IN pin has a higher value and the circuit is susceptible to external noise.					
DATA_IN	Ι	Serial data input pir goes off when input		-	n input data is at a	"H" level, and it		
CLOCK	Ι	Shift clock input pin with the rising edge		_	pin is transferred ir	n synchronization		
LOAD	Ι		Load signal input pin. Serially input data is transferred to the 80-bit latch at "H" level of this load signal, then held at "L" level.					
BLANK	I	Input pin that turns off all segments. The entire display goes off when "L" level is applied to this pin. The display returns to the previous state when "H" level is applied.						
DSEL1 DSEL2	1	Input pins to select selected.	1/3, 1/4, or 1, DSEL2 D L L H	5 duty. Follo SEL1 L H X	wing shows how ea Duty selected 1/3 1/4 1/5 X: Don't ca			
COM1 to COM5	0	Display output pins the LCD panel.	Display output pins for LCD. These pins are connected to the COMMON side of the LCD panel.					
SEG1 to SEG80	0	Display output pins for LCD. Theses pins are connected to the SEGMENT side of the LCD panel. For the correspondence between the output of these pins and input data, see the "Data Structure" Section.						
V <sub>LC1</sub> , V <sub>LC2,</sub> V <sub>LC3</sub>	_	-	Bias pins for LCD driver. Through these pins, bias voltages for the LCD are externally supplied. The bias potential must meet the following condition: $V_{DD} > V_{LC1} \ge V_{LC2} > V_{LC3} = GND$					
$V_{DD}, GND$		Supply voltage pin a	and ground p	in.				

Note: Built-in schmitt circuit is used for all input pins.

#### ABSOLUTE MAXIMUM RATINGS

Parameter S	ymbol	Condition	Rating	Unit
Supply Voltage	V <sub>DD</sub>	Ta = 25°C	-0.3 to 6.5	V
Input Voltage	Vi	Ta = 25°C	–0.3 to V <sub>DD</sub> +0.3 V	
Storage Temperature	T <sub>STG</sub>	_	–55 to 150	°C
Power Dissipation	PD	Ta < 105°C	700	mW
Output Current	lo	_	-2.0 to 2.0	mA

#### **RECOMMENDED OPERATING CONDITIONS**

Parameter S	ymbol	Condition	Range	Unit
Supply Voltage	$V_{\text{DD}}$	V <sub>LC3</sub> = GND	3.0 to 5.5	V
CLOCK Frequency	f <sub>CP</sub>	_	1 to 4	MHz
Operating Temperature	Та	—	-40 to 105	°C

#### **Oscillator Circuit**

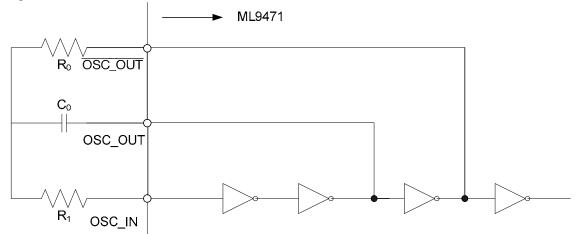
Parameter S	ymbol	Applicable pin	Condition	Min.	Max.	Unit
Oscillator Resistance	R₀	OSC_OUT	_	20	120	kΩ
Oscillator Capacitance	Co	OSC_OUT	—	0.00047	0.01	μF
Current Limiting Resistance	R₁	OSC_IN	—	62	360	kΩ
Common Signal Frequency	f <sub>сом</sub>	COM1 to COM5	—	25	250	Hz

Note: See Section, "Reference Data", for the resistor and capacitor values in the table.

#### **RC Values in Oscillator Circuit**

Parameter	Symbol	Applicable pin	1/3 duty	1/4 duty	1/5 duty	Unit
Oscillator Resistance	$R_0$	OSC_OUT	68	51	43	kΩ
Oscillator Capacitance	C <sub>0</sub>	OSC_OUT	0.001	0.001	0.001	μF
Current Limiting Resistance	R <sub>1</sub>	OSC_IN	220	160	130	kΩ

Example of an oscillator circuit:



### **ELECTRICAL CHARACTERISTICS**

#### **DC Characteristics**

DC Characteristics		(V <sub>DI</sub>	₀ = 3.0 to 5.5 \	/, Ta = -40 to +105°	C, unless ot	herwise spe	cified)
Parameter S	ymbol	Applicable pin	Condition		Min.	Max.	Unit
"H" Input Voltage 1	V <sub>IH1</sub>	CLOCK, OSC_IN		— 0.85	$V_{\text{DD}}$	V <sub>DD</sub> V	
"L" Input Voltage 1	VIL1	CLOCK, OSC_IN	— G		ND	0.15 V <sub>DD</sub>	v
"H" Input Voltage 2	V <sub>IH2</sub>	*1		—	0.8 V <sub>DD</sub>	V <sub>DD</sub>	V
"L" Input Voltage 2	$V_{\text{IL2}}$	*1		—	GND	$0.2 V_{\text{DD}}$	V
"H" Input Current	IIH	All input pins	V <sub>DD</sub> = 5	.5 V, V <sub>I</sub> = V <sub>DD</sub>		10	μA
"L" Input Current	Ι <sub>ΙL</sub>	All input pins	$V_{DD} = 5$	5.5 V, VI = 0 V	-10	—	μA
COMMON Output	$V_{OC0a}$		V <sub>DD</sub> = 3.0 V	I <sub>O</sub> = −100 μA	$V_{\text{DD}}$ –1	_	V
	V <sub>OC1</sub>	COM1 - COM5		I <sub>O</sub> = ±100 μA *3	$V_{LC1} - 1$	V <sub>LC1</sub> +1	V
Voltage	V <sub>OC2</sub>			I <sub>O</sub> = ±100 μA *4	$V_{LC2}$ –1	V <sub>LC2</sub> +1	V
	$V_{OC3}$			I <sub>O</sub> = +100 μA *5	_	V <sub>LC3</sub> +1	V
	V <sub>OS0</sub>			I <sub>O</sub> = −10 μA	$V_{\text{DD}}$ –1	—	V
Segment Output	V <sub>OS1</sub>	SEG <sub>1</sub> - SEG <sub>80.</sub>	V <sub>DD</sub> = 3.0 V	I <sub>O</sub> = ±10 μA *3	$V_{LC1} - 1$	V <sub>LC1</sub> +1	V
Voltage	V <sub>OS2</sub>		VDD 0.0 V	$I_O$ = ±10 $\mu$ A *4	$V_{LC2}$ –1	V <sub>LC2</sub> +1	V
	$V_{OS3}$			I <sub>O</sub> = +10 μA *5	_	V <sub>LC3</sub> +1	V
Supply Current	I <sub>DD</sub>	V <sub>DD</sub>	V <sub>DD</sub> = 5.0	) V, no load. *2	_	0.5	mA

\*1 Applies to all input pins excluding CLOCK and OSC\_IN.

\*2 R  $_0 = 51 \text{ k}\Omega \text{ R}_1 = 160 \text{ k}\Omega \text{ C}_0 = 0.001 \text{ }\mu\text{F}$ 

 $*3 V _{LC1} = 2.0V$ 

\*4 V  $_{LC2} = 1.0V$ 

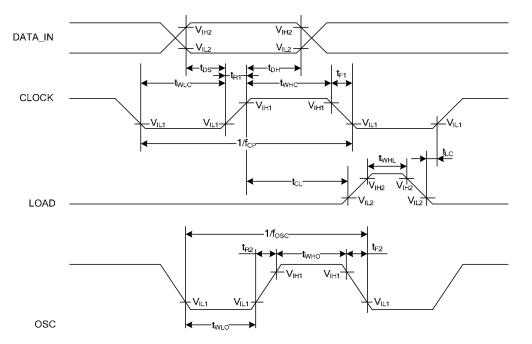
\*5 V = 0V

#### FEDL9471-01

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#### **AC Characteristics**

		(V <sub>DD</sub> =3.0 to 5.5V,	Ta = -40 to +	105°C, unless	s otherwise s	pecified)
Parameter S	ymbol	Condition	Min.	Тур.	Max.	Unit
Clock "H" Time	t <sub>wнc</sub> —		70	_	_	ns
Clock "L" Time	t <sub>wLC</sub> —		70	_	_	ns
Data Set-up Time	t <sub>DS</sub> —		50	_		ns
Data Hold Time	t <sub>DH</sub> —		50		_	ns
Load "H" Time	t <sub>WHL</sub> —		100	—	_	ns
Clock-to-load Time	t <sub>CL</sub> —		100	_	_	ns
Load-to-Clock Time	t <sub>LC</sub> —		100	_		ns
Clock Rise time, Fall time	t <sub>R1</sub> , t <sub>F1</sub> —		_	_	50	ns
OSC_IN Input Frequency	fosc —		_		20	kHz
OSC_IN "H" Time	t <sub>wнo</sub> —		20		_	μS
OSC_IN "L" Time	t <sub>wLO</sub> —		20	_		μS
OSC_IN Rise time, Fall time	t <sub>R2</sub> , t <sub>F2</sub> —		_	_	100	ns

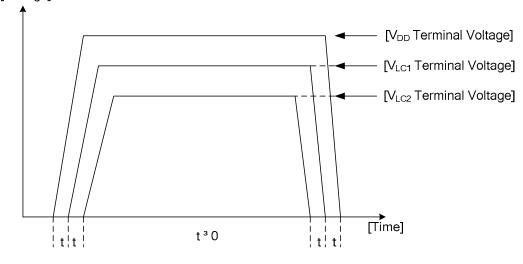


 $\begin{array}{l} (V_{IH1} = 0.85 V_{DD} \ \ V_{IL1} = 0.15 V_{DD}) \\ (V_{IH2} = 0.8 V_{DD} \ \ V_{IL2} = 0.2 V_{DD}) \end{array}$ 

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#### **POWER-ON/OFF TIMING**

[Voltage]



\*  $V_{\text{LC1}}, V_{\text{LC2}}$  are applied when  $V_{\text{DD}}$  is applied to external bias resistor.

#### **INITIAL SIGNAL TIMING**

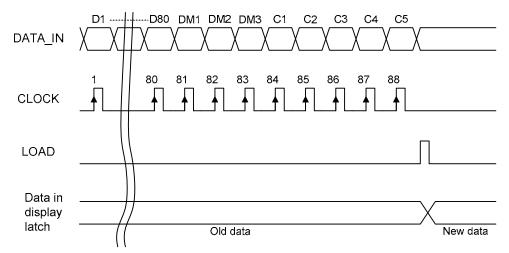


\* On ce V<sub>DD</sub> is applied, <u>BLANK</u> should be applied to 'L' level to make all SEGMENTs off until first group of display data is latched.

#### FUNCTIONAL DESCRIPTION

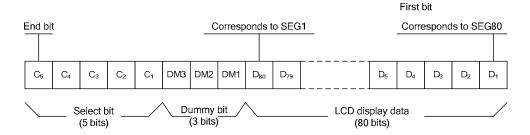
#### Operation

As shown in "Data Structure", the display data consists of the data field corresponding to the output for turning the segments on or off and the select field that selects field that selects the input block of data. Data input to the DATA\_IN pin is loaded into the 88-bit shift register, transferred to the 80-bit latch while the load signal is at "H" level, and then output via the 80-dot segment driver.



#### **Data Structure**

Input data



Correspondence between select bits and COM1 to COM5
---

C5 C	4	C3 C	2	C1	Description
0 0		0 0		1	Display data corresponding to COM1
0 0		0 1		0	Display data corresponding to COM2
0 0		10		0	Display data corresponding to COM3
0 1		0 0		0	Display data corresponding to COM4
10		0 0		0	Display data corresponding to COM5

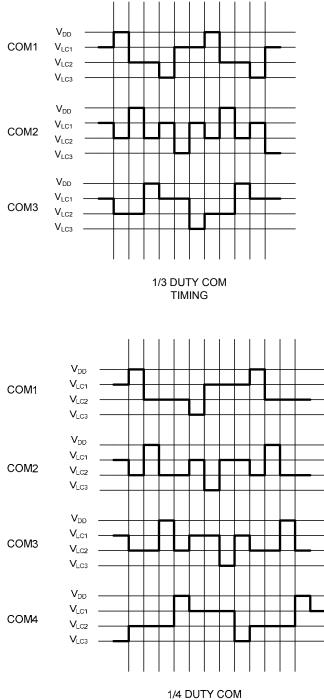
Notes: 1. Arbitrary data can be set for the dummy bits.

2. Select b it,  $C_1$  to  $C_5$ , se lects 8 0-bit latch es t hat co rrespond to COM1 to COM5, res pectively. Therefore, if "1" is set for more than one select bit, data is set to all the corresponding 80-bit latches.

Example:

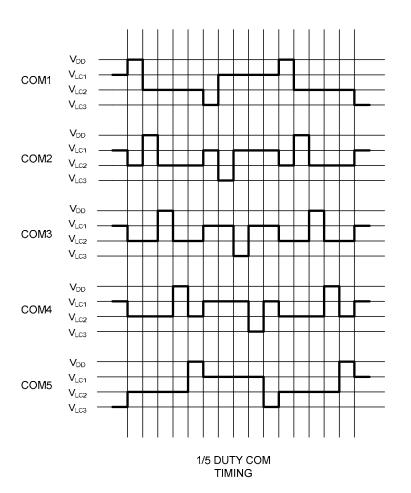
If "1" is set to all the select bits  $C_1$  to  $C_5$ , the display data of  $D_1$  to  $D_{80}$  is set to all the 80-bit latches that correspond to COM1 to COM5.

#### **COM1 – COM5 Timing Chart:**





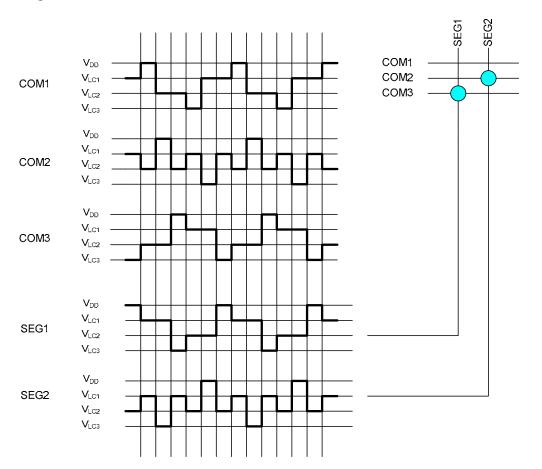
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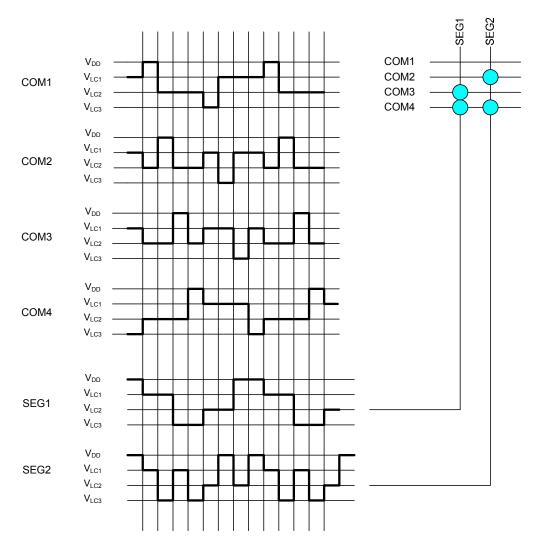
#### SEGn True Value Table:

LATCH1 L	. ATCH2 L	ATCH3 L	ATCH4	LATCH5	COM1	COM2	COM3	COM4	COM5	SEGn
0000	) 1				"H"	"M2" "N	1 2"	"M2" "N	I 2" "N	1 1"
					"L"	"M1" "N	1 1"	"M1" "N	l 1""N	1 2"
					"M2"	"H"	"M2"	"M2" "N	I 2""N	1 1"
					"M1"	"L"	"M1"	"M1" "N	l 1""N	1 2"
					"M2" "N	1 2"	"H"	"M2" "N	I 2""N	1 1"
					"M1" "N	1 1"	"L"	"M1" "N	l 1""N	1 2"
					"M2" "N	1 2" "N	1 2"	"H"	"M2" "N	1 1"
					"M1" "N	1 1""N	1 1"	"L"	"M1" "N	1 2"
					"M2" "N	1 2" "N	12"	"M2"	"H"	"L"
					"M1" "N	1 1""N	1 1"	"M1"	"L"	"H"

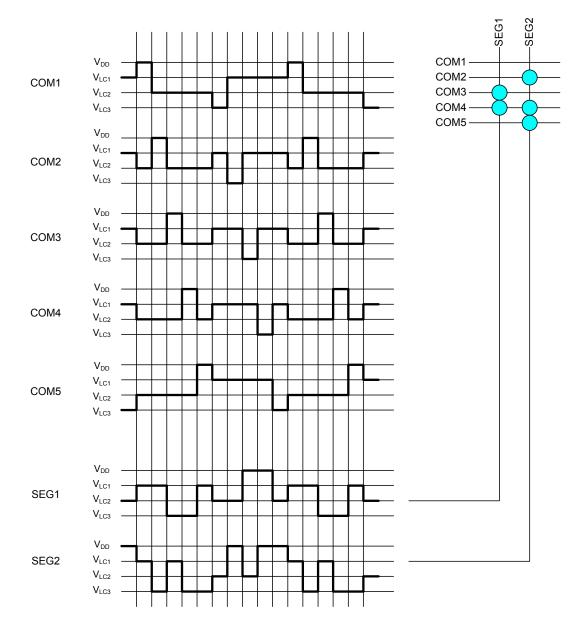
\*Note: "H" =  $V_{DD}$ ; "M1" =  $V_{LC1}$ ; "M2" =  $V_{LC2}$ ; "L" =  $V_{LC3}$ =GND



#### Timing Chart FOR 1/3 DUTY DRIVE MODE:



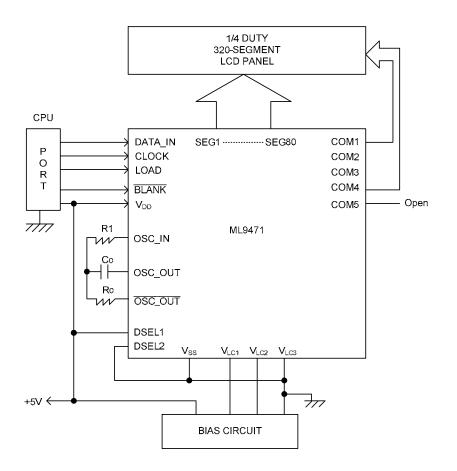
#### **Timing Chart FOR 1/4 DUTY DRIVE MODE:**



#### Timing Chart FOR 1/5 DUTY DRIVE MODE:

## APPLICATION CIRCUITS

(For 1/4 duty)



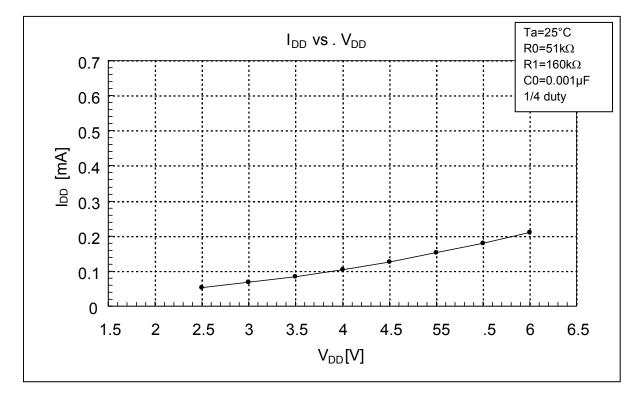
#### **REFERENCE DATA**

The data shown in this section is for reference (a metal film resistor and a film capacitor are u sed). Resistor and capacitor values must be determined based on experiments.

Use the following expression to convert oscillation frequency to COMMON frame frequency (or vice versa):

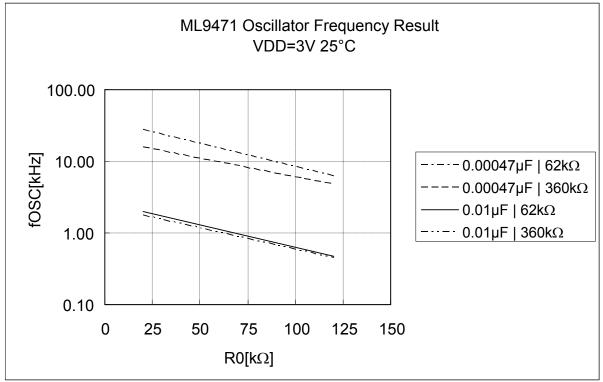
f	COM	: COMMON frame frequency
f	OSC	: Oscillation frequency
	Duty	: e.g., 1/4 for 1/4 duty

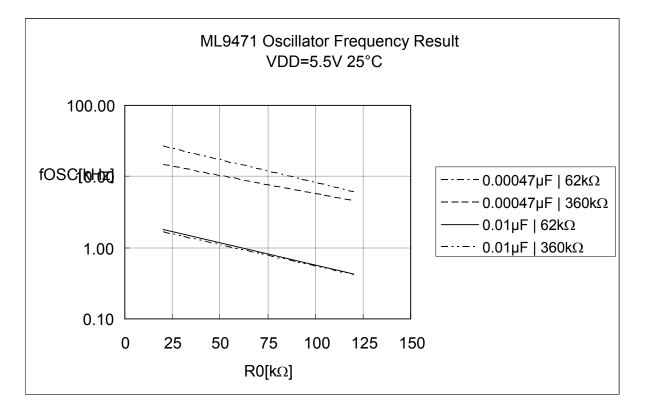
For example, if  $f_{COM}$ =100Hz at 1/5 duty, the oscillation frequency is  $f_{OSC}$ =8000Hz.



ML9471







#### PACKAGE DIMENSIONS

#### TQFP100-P-1414-0.50-K $\Box$ 16, 00 $\pm$ 0, 20 $\Box 14.00\pm0.10$ $1.00 \pm 0.20$ (26) 1. 20MAX. 00±0. INDEX MARK Mirror finish 0.22±0.05 1.00TYP. 0.50 ∄ 0~8' $0.145 \pm 0.05$ $0, 05 \sim 0, 15$ 0.50TYP. $0.60 \pm 0.15$ 0.08 SEATING PLANE Package material Epoxy resin Lead frame material 42 alloy Sn-2Bi (Bi 2% typ.) Lead finish LAPIS Semiconductor Co., Ltd. Pin treatment Solder plating (≥5µm) Package weight (g) Rev. No./Last Revised 0.55 TYP. 1/Jul. 18, 2007

Notes for Mounting the Surface Mount Type Package

The surface mount type packag es are v ery susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before y ou perform reflow mounting, contact R OHM's responsible s ales pers on for the product n ame, pack age n ame, pin num ber, pack age code and desired mounting conditions (reflow method, temperature and times).

#### (Unit: mm)

## **REVISION HISTORY**

		Page		
Document No.	Date	Previous	Current	Description
		Edition	Edition	
PEDL9471-01	Dec. 15, 2006	-	-	Preliminary edition 1
PEDL9471-02	Jan. 15, 2007	-	-	Preliminary edition 2
PEDL9471-03	Jan. 9, 2008	-	Ι	Preliminary edition 3
FEDL9471-01	Aug. 21, 2008	-	_	Final edition 1

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